



—Thermal conductive & electrical insulation—
Adhesive sheet **“EA series”** (High Tg type)

Example of use

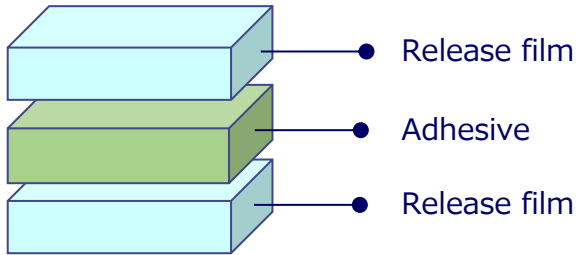
- Power module
- Substrate for LED
- Infrastructure & Substrate for photovoltaics



Characteristics

- Semi-cured adhesive sheet having thermal conductivity and electrical insulation resistance.
- Thickness lineup from 10 to 200μm. (Thickness lineup defers depending on the thermal conductivity level of product)

Product structure



Customization available on customer requests.

Product form

Roll	Sheet

Product Properties

Item	Unit	EAF	EAJ	EAH	EAM	EAP Under development
Characteristics	-	Thin film	For general purpose	High heat dispersion	High heat dispersion	High heat dispersion
Thermal conductivity (LF)	W/m · K	1	3	10	15	18-20
Tg (DMA)	℃	≥200	≥200	≥200	≥200	≥180
Withstand voltage	hr	>1000	>1000	>1000	>1000	—
Thermal shock	Cycle	>1000	>1000	>1000	>1000	—

Sample making conditions: pressing at : 180℃ (60min duration) / 3-20MPa

Withstand voltage conditions : 150℃ / DC1kV

Thermal shock conditions : -40℃⇔150℃



Sales & Marketing Department

Tokyo Head Office: Yanagibashi 2-12-5, Taito-ku, Tokyo 111-0052, Japan Tel : +81-3-3861-1110

Kansai: Tsumori 3-7-27, Nishinari-ku, Osaka 557-0062, Japan Tel : +81-6-4703-3168

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